

H13 GrandTwin

High Density Combined with I/O Flexibility



A+ Server 2115GT-HNTR (with rear I/O)



A+ Server 2115GT-HNTF (with front I/O)

2U, 4-Node-Per-Chassis Flexible Architecture

Maximize resource savings through shared power and cooling

- 4th Gen AMD EPYC™ Processor with up to 3 TB of DDR5-4800 memory per node
- Up to six 2.5" NVMe or SATA drives per node
- PCIe 5.0 with CXL 1.1+ support
- Front I/O configuration enables field service from cold aisle to help reduce downtime
- Flexible networking options with PCIe 5.0 OCP 3.0 interfaces
- Redundant Titanium level shared power supplies

Designed for maximum density, the new GrandTwin™ servers are built on a multi-node architecture for single-processor performance. Powered AMD EPYC™ 9004 Series processors, the servers deliver high performance in a modular design that can be optimized for a wide range of options, with the capability to add or remove components as needed to match data center needs.

Modular Multi-node System with Front or Rear I/O

The new Supermicro multi-node systems are designed for applications that need a large number of discrete servers with high-speed interconnects for networked or clustered operations. They are ideal for virtualized and nonvirtualized applications including:

- **Hyperconverged infrastructure and scale-out storage applications** where a balanced set of resources is key
- **High-performance computing** including EDA simulation, computational fluid dynamics, and weather modeling
- **Content-delivery networks** where a large number of network streams need to run in parallel
- **Back-end infrastructure** for mobile devices including gaming, voice recognition, and mapping services
- **Cloud computing** where a large number of cores are needed to deliver high performance to each virtual machines
- **Big data analytics** that combine scale-out storage with the need for high compute capacity for data analysis

These 2U servers optimize compute, memory, and I/O resources to deliver maximum density—four single-socket nodes in only two rack units. The servers are available with front- or rear-panel I/O options. For the front-panel system, all storage, networking, and node trays are accessible from the cold aisle, simplifying installation and servicing in space-constrained environments.



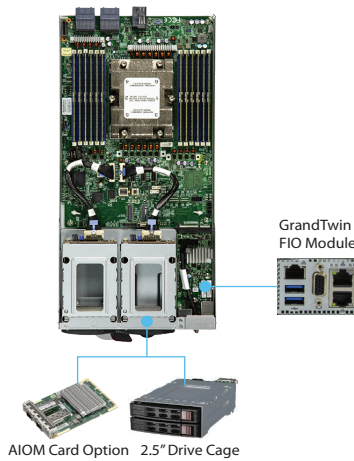
Each of the four nodes host a single AMD EPYC 9004 Series CPU with up to 128 cores, up to 12 DIMMs for a total of 3 TB of DDR5-4800 memory, up to six U.2 NVMe or SATA drives with PCIe 5.0 connectivity, two M.2 slots for boot drives, and a range of networking options to keep data flowing freely through these powerful servers. Dual redundant 2200W power supplies economize on power and cooling.

GrandTwin Front I/O Node

The A+ Server 2115GT-HNTF has all storage and I/O accessible from the front panel for both comfort and ease of servicing in a data center cold aisle. Each node supports up to four U.2 NVMe or SATA drives and a front I/O card with options including dual 10 or 25 Gigabit Ethernet, or single 100 Gigabit Ethernet interfaces. For even more demanding network needs, the rightmost drive bay can be swapped for a Supermicro Advanced I/O Module (AIOM) cage that supports OCP 3.0 interfaces.

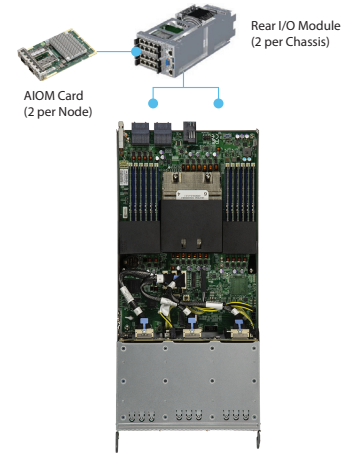
GrandTwin Rear I/O Node

The A+ Server AS -2115GT-HNTR hosts up to six front-panel-accessible U.2 NVMe or SATA drives with all I/O connectivity in the rear of the chassis. There, each node provides two OCP 3.0-standard AIOM expansion slots for your choice of network connectivity.



Open Management

Regardless of your data center’s management approach, our open management APIs and tools are ready to support you. In addition to a dedicated IPMI port, and a Web IPMI interface per node, Supermicro® SuperCloud Composer software helps you configure, maintain, and monitor all of your systems using single-pane-of-glass management. If your DevOps teams prefer to use their own tools, industry-standard Redfish® APIs provide access to higher-level tools and scripting languages.



H13 Generation	Single-Socket AS -2115GT-HNTR GrandTwin Node (Front I/O)	Single-Socket AS -2115GT-HNTR GrandTwin Node (Rear I/O)
Processor Support	<ul style="list-style-type: none"> Single SP5 socket for one AMD EPYC™ 9004 Series processors including those with AMD 3D V-Cache™ technology Up to 128 cores, up to 400W TDP per socket¹ 	<ul style="list-style-type: none"> Single SP5 socket for one AMD EPYC™ 9004 Series processors including those with AMD 3D V-Cache technology Up to 128 cores, up to 400W TDP per socket¹
Memory Slots & Capacity	<ul style="list-style-type: none"> 12-channel DDR5 memory support 24 DIMM slots for up to 3 TB ECC DDR5-4800 RDIMM 	<ul style="list-style-type: none"> 12-channel DDR5 memory support 24 DIMM slots for up to 3 TB ECC DDR5-4800 RDIMM
On-Board Devices	<ul style="list-style-type: none"> System on Chip NVMe and 6 Gbps SATA3 storage interfaces via AMD EPYC processor IPMI 2.0 with virtual-media-over-LAN and KVM-over-LAN support ASPEED AST2600 BMC graphics 1 TPM 2.0 header 	<ul style="list-style-type: none"> System on Chip NVMe and 6 Gbps SATA3 storage interfaces via AMD EPYC processor IPMI 2.0 with virtual-media-over-LAN and KVM-over-LAN support ASPEED AST2600 BMC graphics 1 TPM 2.0 header
I/O Ports	Choice of GrandTwin Front I/O modules; each includes dedicated RJ45 IPMI LAN port, 2x USB 3.0, VGA connector plus: <ul style="list-style-type: none"> Dual RJ45 1/10 GbE Ports (AOC-GTG-I2T) Dual SFP28 25 GbE Ports (AOC-G25G-M2S) Single QSFP 100 GbE Port (AOC-G100G-X1C) 	<ul style="list-style-type: none"> 1 RJ45 Dedicated IPMI LAN port per node Shared (switchable) interfaces for each pair of nodes: <ul style="list-style-type: none"> 2 USB 3.0 ports 1 VGA
Drive Bays	<ul style="list-style-type: none"> 4 hot-pluggable 2.5" drive bays for U.2 NVMe or SATA3 drives 2 M.2 NVMe/SATA3 2280 slots 	<ul style="list-style-type: none"> 6 hot-pluggable 2.5" drive bays for U.2 NVMe or SATA3 drives 2 M.2 NVMe/SATA3 2280 slots
Expansion Slots	<ul style="list-style-type: none"> Drive cage can be swapped out for an OCP 3.0 AIOM card bay 	<ul style="list-style-type: none"> 2 AIOM/OCP 3.0 with NCSI
BIOS	<ul style="list-style-type: none"> AMI 256 Mb (32 MB) SPI Flash ROM 	<ul style="list-style-type: none"> AMI 256 Mb (32 MB) SPI Flash ROM
System Management	<ul style="list-style-type: none"> Built-in server management tool (IPMI 2.0, KVM/media over LAN) with dedicated LAN port Redfish APIs Supermicro SuperCloud Composer Supermicro Server Manager (SSM) and Supermicro Update Manager (SUM) 	<ul style="list-style-type: none"> Built-in server management tool (IPMI 2.0, KVM/media over LAN) with dedicated LAN port Redfish APIs Supermicro SuperCloud Composer Supermicro Server Manager (SSM) and Supermicro Update Manager (SUM)
Chassis	CSE-GT214BF-R2K21BP2	CSE-GT214BC-R2K21BP
Form Factor	<ul style="list-style-type: none"> 2U rackmount 	<ul style="list-style-type: none"> 2U rackmount
Front Panel	<ul style="list-style-type: none"> On/off and Universal Information (UID) buttons Power status and UID LEDs 	<ul style="list-style-type: none"> On/off and Universal Information (UID) buttons Power status and UID LEDs
Shared Power & Cooling	<ul style="list-style-type: none"> 2 heavy duty 8 cm PWM fans Redundant 2200W Titanium Level power supplies 	<ul style="list-style-type: none"> 2 heavy duty 8 cm PWM fans Redundant 2200W Titanium Level power supplies

¹Certain CPUs with high TDP may be supported only under specific conditions. Please contact Supermicro Technical Support for additional information about specialized system optimization